### **Overview**



- 1. Power Button
- 2. System Activity LED
- 3. Thunderbolt™ 2\* (2 ports)
- 4. SD 4.0 Media Card Reader

- 5. USB 3.0 (2 ports, upper charging, lower standard)
- 6. Headphone port
- 7. Microphone port

\*Thunderbolt is new technology. Thunderbolt cable and Thunderbolt device (sold separately) must be compatible with Windows. To determine whether your device is Thunderbolt Certified for Windows, see <a href="https://thunderbolttechnology.net/products">https://thunderbolttechnology.net/products</a>. Thunderbolt™ 2.0 is planned to be available via an optional add-in card in early 2014.

Form Factor	All in One
Operating Systems	Windows 8.1 Pro 64-bit
	Genuine Windows® 7 Professional 64-Bit(1)
	Windows 8.1 Pro Downgrade to Windows 7 Professional 64-bit
	Windows 8.1 Pro MSNA 64 Downgrade to Windows 7 Professional 64-bit
	HP Linux Installer Kit(2)
	SUSE Linux Enterprise Desktop 11 (90 day license) (4)



#### Overview

Red Hat Enterprise Linux Desktop/Workstation (3,4)

**NOTE 1:** Systems may require upgraded and/or separately purchased hardware and/or DVD drive to install the Windows 7 software and take full advantage of Windows 7 functionality. See <a href="http://www.microsoft.com/windows/windows-7/">http://www.microsoft.com/windows/windows-7/</a> for details.

**NOTE 2:** HP Linux Installer Kit Includes drivers for 32-bit and 64-bit OS versions of Red Hat Enterprise Linux (RHEL) 5 Workstation, RHEL 6 Workstation, and 64-bit SUSE Linux Enterprise Desktop (SLED) 11. See <a href="http://www.hp.com/go/linux">http://www.hp.com/go/linux</a> for details.

**NOTE 3:** RHEL Desktop is not available as a preinstall from HP. RHEL Desktop is only available as a oneyear paper license drop-in-the-box.

**NOTE 4:** For detailed OS/hardware support information for Linux, see:

http://www.hp.com/support/linux hardware matrix.

#### **Available Processors**

Name	Cores	Clock Speed (GHz)	Boost	Cache (MB)	Memory Speed (MHz)	Hyper- Threading	Featuring Intel® vPro™ Technology	Intel® HD Graphics	TDP (W)
Intel® Xeon® processor E3-1280v3	4	3.6	4.0	8	1600	Y	Υ	N/A	82W
Intel® Xeon® processor E3-1245v3	4	3.4	3.8	8	1600	Y	Y	Intel HD Graphics P4600	84W
Intel® Xeon® processor E3-1225v3	4	3.2	3.6	8	1600	N	Υ	Intel HD Graphics P4600	84W
Intel® Core™ i5- 4570 processor	4	3.2	3.6	6	1600	N	Υ	Intel HD Graphics 4600	84W
Intel® Core™ i3- 4130 processor	2	3.4	N/A	3	1600	Y	N	Intel HD Graphics 4400	54W

<sup>1</sup>The specifications shown in this column represent the maximum frequency (GHz) of one processor core when accelerated with Intel Turbo Boost Technology. Turbo boost stepping occurs in 100MHz increments. Processors that do not have turbo functionality are denoted as N/A.

### Available Processor Disclaimers

Intel Xeon E3 and Intel Core i3 processors can support either ECC or non-ECC memory.

Intel's numbering is not a measurement of higher performance. Processor numbers differentiate features within each processor family, not across different processor families. See:

http://www.intel.com/products/processor\_number/ for details.

64-bit computing on Intel® 64 architecture requires a computer system with a processor, chipset, BIOS, operating system, device drivers and applications enabled for Intel 64 architecture. Processor will not operate (including 32-bit operation) without an Intel 64 architecture-enabled BIOS. Performance will vary depending on your hardware and software configurations. See: http://www.intel.com/info/em64t for more information.

Dual-Core and Quad-Core technologies are designed to improve performance of multithreaded software products and hardware-aware multitasking operating systems and may require appropriate operating system software for full benefits; check with software provider to determine suitability; Not all customers or software applications will necessarily benefit from use of these technologies.

#### Integrated Display

See below for detailed information

Panel

### Overview

Internal I/O	1 USB 2.0 Type A on Rear IO board, 2 internal on 9-pin header (not available on touch capable option)
Internal I/O	Headphone, 1 Microphone  1 USB 2 O Type A on Pear IO heard, 2 internal on 9-pin header (not available on touch capable option)
Side I/O	1 USB 3.0, 1 USB 3.0 Charging Data Port, 2 Thunderbolt™ 2 ports (Optional),1 SD 4.0 Media Card Reader, 1
storage section for more details)	• 2 internal 2.5" bays
Expansion Bays (see	• 1 internal 3.5" bay, or
more details)	
system board section for	2 miniPCIe/mSATA full-length
Expansion Slots (see	industry standard VESA mount. The VESA mount on the Z1 uses a 100x100 VESA mount pattern.  • 1 MXM 3.1 (dedicated for graphics)
Convertibility	The Z1 can either be placed on the desktop in the traditional display method or mounted on a wall with the
	<ul> <li>Resolution: 25 pixels-per-inch minimum (Win8)</li> <li>Accuracy: 1 mm to each target &amp; 10% jitter limit on moving (Win 8)</li> <li>Anti-glare: No glass, anti-glare as CTO option</li> </ul>
	Input: Finger or Capacitive Stylus
	<ul> <li>Multi-Touch: 10 points</li> <li>Technology: Projected Capacitive Touch</li> </ul>
	O Sensor Panel: 27"Glass on Glass
	Z1 G2 Touch Technology:
	<ul> <li>Default Color Temperature: 6500 K</li> <li>Touch: 10 finger touch as CTO option (no pen ability)</li> </ul>
	User Programmable Modes: None     Default Color Torrespondence (SEO) K
	Maximum Pixel Clock Speed: 250 MHz
	<ul> <li>Native Resolution: 2560 x 1440 @ 60 Hz; 3.7MP</li> <li>Preset VESA Graphic Modes (non-interlaced): 2560 x 1440 @ 60 Hz</li> </ul>
	Vertical Frequency: 60 H  Native Possiution: 2560 v 1440 @ 60 Hz: 3 7MP
	Horizontal Frequency: 90 kHz
	Signal Interface/Performance
	Notes: Color Support **: Up to 16.7 Million colors
	Notes: *All performance specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.
	<ul> <li>Color Gamut Coverage of sRGB: 100% (CIE 1931)</li> <li>Color Support **: Up to 16.7 Million colors</li> </ul>
	Color Gamut Area vs. NTSC: 77% (CIE 1931)     Color Gamut Gazara of a BCR: 100% (CIE 1931)
	Backlight LED Life Time: 30,000 hours minimum
	Pixel Pitch: 0.2331 mm x 0.2331 mm
	<ul> <li>Dynamic Contrast Ratio (typical)*: N/A</li> <li>Response Time (typical)*: 14 ms (gray to gray)</li> </ul>
	Contrast Ratio (typical)*: 1000:1      Description Contract Ratio (typical)*: N/A
	Minimum Brightness (typical)*: 50 nits cd/m²
	Maximum Brightness (typical)*: 380 nits cd/m²
	<ul> <li>Aspect Ratio: 16:9 Widescreen</li> <li>Viewing Angle (typical): Up to 178° horizontal / 178° vertical</li> </ul>
	Optimal Resolution: 2560 x 1440 @ 60 Hz; 3.7MP  Asset Batis 16:0 Wides was as
	<ul> <li>Screen Opening (W x H): 59.8 x 33.6 cm, (23.5 x 13.3 in.)</li> </ul>
	Viewable Image Area: 68.5 cm, (27 in.) widescreen; diagonally measured  Screen Opening (W. V.) 50.8 x 23.6 cm, (23.5 x 13.3 in.)



### Overview

Rear I/O	1 DisplayPort v1.1, 4 USB 2.0, 1 RJ45 LAN, 1 Subwoofer Output, 1 optical S/PDIF Output, 1 Audio Line-in, and 1 Audio Line-out			
<b>Chassis Dimensions</b> (HxWxD)	Vertical display orientation WITH stand: 530.0mm x 660.4mm x 419.1mm (20.8in. x 26in. x 16.5in.);  Standard display orientation WITHOUT stand: 457.2mm x 660.4mm x 81.28mm (18in. x 26in. x 3.2in.)  Service/Shipping orientation: 116mm x 660mm x 510mm			
Weight	Exact weights depend upon configuration; Max system weight WITH stand: 21.32 kg (47 lbs); Stand weight 5.9 kg (13 lbs)			
Temperature	Operating: Non-operating	40° to 95°F (5° to 35°C) -40° to 140°F (-40° to 60°C)		
Humidity	Operating: Non-operating	8% to 85% 8% to 90%		
Maximum Altitude (non- pressurized)	Operating: Non-operating	3,000 m (10,000 ft) 9,100 m (30,000 ft).		
Power Supply	The Power Supply Efficien	ctive Power Factor Correction, 90% Efficient  cy Report for this product may be found at these links: tions.com/psu_reports/HEWLETT%20PACKARD_650503-  OW_Report.pdf		
Chipset	Intel® C226 chipset			
Memory	4 DIMM slots, supporting (	up to 32GB ECC or 16GB non-ECC Unbuffered DDR3 1866 MHz Components.		
Memory Disclaimers	The CPU determines the speed at which the memory is clocked. If a 1600MHz capable CPU is used in the system, the maximum speed the memory will run at is 1600MHz regardless of the specified speed of the memory.			
Workstation ISV Certifications	See the latest list of certif	ications at: d-states/campaigns/workstations/partnerships.html		



### **Supported Components**

Processors		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	Intel® Xeon® processor E3-1200 v3 family (Z230/Z1G2)				
	Intel® Xeon® processor E3-1280v3, Quad-Core, 8 MB cache, 3.6 GHz, up to 4.0 GHz with Intel Turbo Boost Technology	Υ	N		Note 1
	Intel® Xeon® processor E3-1245v3, Quad-Core, 8 MB cache, 3.4 GHz, up to 3.8 GHz with Intel Turbo Boost Technology	Υ	N		Note 1, 2
	Intel® Xeon® processor E3-1225v3, Quad-Core, 8 MB cache, 3.2 GHz, up to 3.6 GHz with Intel Turbo Boost Technology	Υ	N		Note 1, 2
	4th generation Intel® Core™ processor family				
	Intel® Core™ i3-4130 processor, Dual-Core, 4 MB cache, 3.4 GHz	Υ	N		Note 1
	Intel® Core™ i5-4570 processor, Quad-Core, 6 MB cache, 3.2 GHz, up to 3.6 GHz with Intel Turbo Boost Technology	Υ	N		Note 3

**NOTE 1:** These processors support either ECC or non-ECC memory

**NOTE 2:** Intel HD Graphics P4600 provides improved desktop performance and supports workstation-specific graphics drivers for improved compatibility and performance on select professional applications compared to Intel HD Graphics 4600 or Intel HD Graphics 4400.

**NOTE 3:** These processors support only non-ECC memory

Monitors / Displays		Factory Configured Option Kit	Option Kit Part Number	Support Notes
	HP DreamColor LP2480zx Professional Display			
	HP Z Display Z30i 30-inch IPS LED Backlit Monitor			
	HP Z Display Z27i 27-inch IPS LED Backlit Monitor			
	HP Z Display Z24i 24-inch IPS LED Backlit Monitor			
	HP Z Display Z23i 23-inch IPS LED Backlit Monitor			
	HP Z Display Z22i 21.5-inch IPS LED Backlit Monitor			
	NOTES:			
	Supported by all Operating Systems available from HP			
	Screen Size Diagonally Measured			



### **Supported Components**

#### Storage / Hard Drives

SATA Hard Drives		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	SATA Hard Drives for HP Workstations				
	500GB SATA 7200 rpm 6Gb/s 3.5" HDD	Υ	Υ	LQ036AA	
	1TB SATA 7200 rpm 6Gb/s 3.5" HDD	Υ	Υ	LQ037AA	
	2.0TB SATA 7200 rpm 6Gb/s 3.5" HDD	Υ	Υ	QB576AA	
	3.0TB SATA 7200 rpm 6Gb/s 3.5" HDD	Υ	Υ	QF298AA	
	500GB SATA 10K rpm SFF HDD	Υ	Υ	B8X19AA	
	1TB SATA 10K rpm SFF HDD	Υ	Υ	B8X20AA	
SATA SSDs	<b>HP Solid State Drive for Workstations</b>				
	HP 256GB SATA 6Gb/s SSD	Υ	Υ	A3D26AA	
	HP 512GB SATA 6Gb/s SSD	Υ	Υ	D8F30AA	
	Seagate 600 Pro 480GB SATA SSD	Υ	Υ	E9Q52AA	
	Seagate 600 Pro 120GB SATA SSD	Υ	Υ	E9Q50AA	
	Seagate 600 Pro 240GB SATA SSD	Υ	Υ	E9Q51AA	
	HP 256GB mSATA 6Gb/s SSD	Υ	Υ	E5Z78AA	

Hard Drive Controllers			<b>Option Kit</b>	
	Factory		Part	Support
	Configured	Option Kit	Number	Notes

### Factory integrated RAID on motherboard for SATA drives

RAID 0 Configuration - Striped Array Y N
RAID 1 Configuration - Mirrored Array Y N

SATA hardware RAID is not supported on Linux systems. The Linux kernel, with built-in software RAID, provides excellent functionality and performance. It is a good alternative to hardware-based RAID. Please visit http://h20000.www2.hp.com/bc/docs/support/SupportManual/c00060684/c00060684.pdf for RAID capabilities with Linux.

All drives must be identical in type and capacity

All RAID arrays must be less than 2 TB

**NOTE 1:** Requires identical hard drives (speeds, capacity, interface).



### **Supported Components**

Graphics		Factory Configured	Option Kit	Option Kit Part Number	Support Notes	Supported Multi Mixed
Integrate	d Intel HD Graphics (Z230/Z1G2)					
Intel HD G	raphics P4600	Y	N		NOTE 1. Supported on Intel Xeon E3- 12x5v3 processors only.	1
Intel HD G	raphics 4600	Y	N		NOTE 1. Supported on Intel Core i5- 4xxx and Core i7-4xxx processors only.	1
Intel HD G	raphics 4400	Y	N		NOTE 1. Supported on Intel Core i3- 4xxx processors only	1
Entry 3D						
NVIDIA Qu <b>Mid-rang</b>	adro K610M 1GB Graphics e <b>3D</b>	Υ	Υ	E5Z74AA		1
NVIDIA Qu <b>High End</b>	adro K2100M 2GB Graphics 3D	Υ	Υ	E5Z75AA		1
NVIDIA Qu	adro K3100M 4GB Graphics	Υ	Υ	E5Z76AA		1
NOTE 1:	nadro K4100M 4GB Graphics te graphics card is installed, Intel i	<b>Y</b> ntegrated gra	Y phics is di	E5Z77AA sabled.		1



### Supported Components

Memory CTO Option Kit Part Support Notes
Number

#### DDR3-1866 ECC Unbuffered DIMMs - CTO

HP 32GB (4x8GB) DDR3-1866 ECC RAM

HP 16GB (2x8GB) DDR3-1866 ECC RAM

HP 16GB (4x4GB) DDR3-1866 ECC RAM

HP 8GB (2x4GB) DDR3-1866 ECC RAM

HP 8GB (4x2GB) DDR3-1866 ECC RAM

HP 4GB (2x2GB) DDR3-1866 ECC RAM

HP 4GB (1x4GB) DDR3 1866 ECC RAM

#### DDR3-1866 nECC Unbuffered DIMMs CTO

HP 16GB (4x4GB) DDR3-1866 nECC RAM

HP 8GB (2x4GB) DDR3-1866 nECC RAM

HP 4GB (1x4GB) DDR3-1866 nECC RAM

#### **Sub-Section Description/Notes**

Intel® Xeon E3 and Intel Core i3 processors can support either ECC or non-ECC memory; Intel® Core i5/i7 processors only support non-ECC memory.

Two channels of DDR3 memory are supported. To realize full performance at least one DIMM must be inserted into each channel.

The CPU determines the speed at which the memory is clocked. If a 1333MHz capable CPU is used in the system, the maximum speed the memory will run at is 1333MHz regardless of the specified speed of the memory.

Only unbuffered DDR3 DIMMs are supported.

#### **AMO**

#### DDR3-1866 ECC Unbuffered DIMMs - AMO

 HP 8GB (1x8GB) DDR3-1866 ECC RAM
 E2Q93AA

 HP 4GB (1x4GB) DDR3-1866 ECC RAM
 E2Q91AA

 HP 2GB (1x2GB) DDR3-1866 ECC RAM
 E2Q90AA

#### DDR3-1866 nECC Unbuffered DIMMs AMO

HP 4GB (1x4GB) DDR3-1866 nECC RAM E5Z83AA

#### **Sub-Section Description/Notes**

The CPU determines the speed at which the memory is clocked. If a 1600MHz capable CPU is used in the system, the maximum speed the memory will run at is 1600MHz regardless of the specified speed of the memory.

The CPU determines the speed at which the memory is clocked. If a 1600MHz capable CPU is used in the system, the maximum speed the memory will run at is 1600MHz regardless of the specified speed of the memory.



### **Supported Components**

<b>Multimedia and Audio</b>			<b>Option Kit</b>	•
Devices		Factory	Part	Support
		Configured Option Kit	Number	Notes
	HP HD 2MP 1080p Webcam	Y N		
	Integrated HP Digital Mic Array	Y N		

Optical and Removable Storage		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP Slim DVD-ROM Drive	Υ	Υ	E5Z82AA	
	HP Slim SuperMulti DVDRW SATA Drive	Υ	Υ	E5Z80AA	
	HP Slim Blu-rav Writer	Υ	Υ	E5Z81AA	

Actual speeds may vary. Does not permit copying of commercially available DVD movies or other copyright protected materials. Intended for creation and storage of your original material and other lawful uses. Double Layer discs can store more data than single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players. As Blu-ray is a new format containing new technologies, certain disc, digital connection, compatibility and/or performance issues may arise, and do not constitute defects in the product. Flawless playback on all systems is not guaranteed. In order for some Blu-ray titles to play, they may require a DVI or HDMI digital connection and your display may require HDCP support. HD-DVD movies cannot be played on this workstation.

Controller Cards		Factory Configured		Option Kit Part Number		
	HP Thunderbolt 2-port AiO Module	Υ	Υ	E5Z73AA		
Networking and Communications		Factory Configured	Option Kit	Option Kit Part Number	Support Notes	
	Integrated Intel I217LM PCIe GbE Controller (Intel vPro with Intel AMT 9.0)	Υ	N			
	Integrated Intel Dual Band Wireless-AC 7260, Dual Band with dual antenna TX/RX streams at 867Mbps 802.11ac Wireless LAN & Bluetooth®4 Combo Card NOTE 1: Card is factory installed into miniPCIe slot 1.	Y	N			



### **Supported Components**

Racking and Physical Security		Facto Configu	-	ion Kit	Option Kit Part Number	Support Notes
	HP Chassis Intrusion Sensor	Υ		N		
	HP Keyed Cable Lock Kit	N		Υ	BV411AA	
Input Devices					Option Kit	:
		Facto	-		Part	Support
		_	red Opt	ion Kit	Number	Notes
	HP USB CCID SmartCard Keyboard	Υ		Υ	E6D77AA	
	HP USB Keyboard	Υ		Υ	QY776AA	
	HP Wireless Keyboard and Mouse	Υ		Υ	QY449AA	
	HP USB Laser Mouse	Υ		Υ	GW405AA	
Other Hardware					Option Kit	
		Facto	-		Part	Support
		Configu	red Opt	ion Kit	Number	Notes
	HP Power Cord Kit	Υ		N		
	HP ENERGY STAR Qualified Configuration	Υ		N		
Software		Factory Configured	Option Kit	Kit	tion Part nber Sup	port Notes
	HP Performance Advisor	γ	N		-	ee note 1
	HP Remote Graphics Software (RGS) 6.0	Ү	N		_	ee note 2
	PDF Complete - Corporate Edition	Υ	N		٠,	
	MS Office Home & Business 2013	, Y	N		Ç	ee note 3
	NOTE 1: Available as a free download here: www.hp.c	•		isor	٠,	ec note 3
	NOTE 1: Available as a free download free. www.hp.c NOTE 2: Supports both 32 and 64 bit versions of Wind Professional and Enterprise, and RHEL V6 NOTE 3: Available CTO as a "Drop in the Box" addition	dows 7 Professio			orise, Windo	ws XP



### **Supported Components**

### Operating Systems Support Notes

Genuine Windows® 7 Professional 64-bit See note 1
HP Linux Installer Kit See note 2
SUSE Linux Enterprise Desktop 11 See note 2
Red Hat Enterprise Linux (RHEL) Workstation - Paper License (1yr) See note 3

Windows 8.1 Pro Downgrade to Windows 7 Professional 64-bit

Windows 8.1 Pro 64-bit

Windows 8.1 Pro Downgrade to Windows 7 Professional 64-bit (National Academic)

**NOTE 1:** See http://www.microsoft.com/windows/windows-7/ for support details.

**NOTE 2:** For detailed OS/hardware support information for Linux, see:

http://www.hp.com/support/linux\_hardware\_matrix.

**NOTE 3:** This second OS must be ordered with the HP Linux Installer Kit as the first OS.



System Board							
System Board Form Factor	Custom Motherboard, Custom Rear IO boo	ard, Custom Side IO board					
Processor Socket	Single LGA 1150						
CPU Bus Speed	DMI Gen2	I Gen2					
Chipset	Intel® PCH C226	el® PCH C226					
Super I/O Controller	Nuvoton NPCD379H						
Memory Expansion Slots	4 DDR3 memory slots						
Memory Type Supported	DDR3, UDIMM (Unbuffered), ECC & non-EG	CC C					
Memory Modes	Non-interleaved for single channel. Interleaved when both channels are popu	lated.					
Memory Speed Supported	Up to 1600MHz DDR3						
Maximum Memory	32GB ECC or 16GB non-ECC						
Memory Configuration (Supported)	4GB non-ECC/ 2GB, 4GB and 8GB ECC unb ECC and non-ECC memory DIMMs cannot	be mixed on the same system.					
	<b>NOTES:</b> * Maximum memory capacities assume 64-bit operating systems, such as genuine Genuine Windows® 7 Professional 64-Bit or Red Hat Linux 64-bit. 32-bit Windows Operating Systems support up to 4 GB.						
PCI Express Connectors	1 MXM 3.1 slot (PCIe Gen2 x16, DP x 2) for graphics 2 miniPCIe/mSATA slots (PCIe Gen2 x1 or SATA 6Gbps x1, USB 2.0), full length  NOTE: the Z1 G2 ships with an Intel WLAN/BT card installed in slot 1.						
Supported Drive Interfaces	SATA	Integrated Serial ATA interfaces: 2 x 6Gb/s SATA, 1 x 6Gb/s SATA for ODD 2 x mSATA/miniPCIe slots  NOTE: the Z1 supports a maximum of two SATA SFF/SSD drives only. RAID 0 and 1 supported. (Factory integrated RAID is Microsoft Windows only).  NOTE: the Z1 G2 ships with an Intel WLAN/BT card installed in slot 1.					
	Integrated RAID	NOTE: Requires identical hard drives (speeds, capacity, interface)					
	Integrated Graphics	Intel HD Graphics P4600 (on Intel Xeon E3-12x5v3 processors) Intel HD Graphics 4600 (on Core i5-4570 processor) Intel HD Graphics 4400 (on Core i3-4130 processor) Unified Memory Architecture (UMA)- A region of system memory is reserved and dedicated to the graphics display.  DirectX 11.1 compliant and OpenGL 4.0. Integrated Graphics can support up to 3 displays: embedded					
		display, external display via Rear IO and external display via optional add-in TBT module.					



### **System Technical Specifications**

	Network Controller Integrated Ethernet PHY Connection I217LM. Manager capabilities: WOL, PXE 2.1 and AMT 9					
USB Connector(s)	Front	Side (not Front): 1 USB 3.0, 1 USB 3.0 Charging Data Port				
	Rear	4 USB 2.0				
	Internal	1 USB 2.0 Type A, 2 USB 2.0 across one 9-pin header (9-pin header is not available when the touch display option is selected)				
HD Integrated Audio	Intel HD / IDT 92HD68 codec					
Flash ROM	Yes					
CPU Fan Header	/es					
Front Control Panel/Speaker Header	Yes					
CMOS Battery Holder - Lithium	Yes	res				
Integrated Trusted Platform Module	Integrated TPM 1.2.  TPM module disabled where restricted by	law.				
Power Supply Headers	Yes	tuw.				
Power Switch, Power LED & Hard Drive LED Header	Yes					
Clear Password Jumper	Yes					
Keyboard/Mouse	USB or Wireless					

### **Power Supply**

Power Supply	400W 90% Efficient, Custom PSU (Wide Ranging, Active PFC)		
Operating Voltage Range	90-264 VAC		
Rated Voltage Range	100-240 VAC	118 VAC	
Rated Line Frequency	50-60 Hz	400 Hz	
Operating Line Frequency Range	47-63 Hz	393-407 Hz	
Rated Input Current	5A @ 100-240 VAC	4.5A @ 118 VAC	
Heat Dissipation (Configuration and software dependent)	Typical: 570 btu/hr (144 kg-cal/hr) Maximum: 1365 btu/hr (344 kg-cal/hr)		
Power Supply Fan	(2) 40x20 mm v	variable speed	
ENERGY STAR Qualified (Configuration dependent)	Yes		
80 PLUS® Compliant	Yes, 90% Efficient		
	The Z1 400W power supply efficiency report can be found at this link: http://www.plugloadsolutions.com/psu_reports/HEWLETT%20PACKARD_650503-001_ECOS%202720.1_400W_Report.pdf		



### **System Technical Specifications**

FEMP Standby Power Compliant @115V	Yes
ErP LOT6 Compliant @ 230V (<0.5 W in S5 - Power Off)	Yes
CECP Compliant @ 220V (<4W in S3 - Suspend to RAM)	NA
Power Consumption in sleep mode (as defined by ENERGY STAR) - Suspend to RAM (S3) (Instantly Available PC)	<4W
Built-in Self Test LED	Yes
Surge Tolerant Full Ranging Power Supply (withstands power surges up to 2000V)	Yes

### **System Configuration**

Example Configuration #1	Drocessor Info	1xIntel Core i3-4130					
Example Conjugatation #1	Memory Info	HP 8GB (2x4GB) DDR3 1866 ECC RAM					
	Graphics Info		10M Graphics				
	Disks/Optical/Floppy		ΓΑ/1xDVD-RO				
	Power Supply	400W 90% C		MIDAIA			
	Other	400W 30% C	ustonii P30				
	ottiei	445	1/46	220	1/46	100	1/46
Energy Consumption			VAC		VAC		VAC
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	70 W 70 W 71 W			W		
	Windows Busy Typ (S0)	108 W 110 W 110 W			) W		
	Windows Busy Max (S0)	142 W 139 W 143 W		3 W			
	Sleep (S3)	0.82 W 0.82 W 0.97 W 0.82 W 0.82 W		0.97 W			
	Off (S5)	0.74 W 0.74 W 0.89 W 0.74 W 0.74 W 0.89 W			0.89 W		
	Zero Power Mode (EuP)	0.20 W 0.35 W 0.19 W					
Heat Dissipation**		115	VAC	230	VAC	100	VAC
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	239 E	Btu/hr	239 Btu/hr 242 Btu/hr		Btu/hr	
	Windows Busy Typ (S0)	369 E	Stu/hr	375 Btu/hr 375 Btu/hr			
	Windows Busy Max (S0)	) 485 Btu/hr 474 Btu/hr 488 Btu/hr		Stu/hr			
	Sleep (S3)	2.80 Btu/hr   2.80 Btu/hr   3.31 Btu/hr   2.80 Btu/hr   2.80 Btu/hr   3.31 Btu			3.31 Btu/hr		
	Off (S5)	2.52 Btu/hr	2.52 Btu/hr	3.04 Btu/hr	2.52 Btu/hr	2.52 Btu/hr	3.04 Btu/hr
	Zero Power Mode (EuP)	0.68 E	Btu/hr	1.19 E	Stu/hr	0.65 E	Btu/hr



Example Configuration #2	Processor Info	1xIntel Xeon	E3-1280v3					
	Memory Info	HP 8GB (2x4GB) DDR3 1866 ECC RAM						
	Graphics Info	1xNVIDIA K3	1xNVIDIA K3100M Graphics					
	Disks/Optical/Floppy	1x1TB SATA/	1xDVD+-RW	SATA				
	Power Supply	400W 90% C	ustom PSU					
	Other	-						
Energy Consumption		115	VAC	230	VAC	100	VAC	
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows Idle (S0)	74	W	73	W	75	W	
	Windows Busy Typ (S0)	) 167 W 171 W 174 W			1 W			
	Windows Busy Max (S0)	24	4 W	237 W 242 W		2 W		
	Sleep (S3)	0.83 W	0.83 W	0.98 W	0.83 W	0.83 W	0.98 W	
	Off (S5)	0.74 W 0.74 W 0.89 W 0.74 W 0.74 W 0.89			0.89 W			
	Zero Power Mode (EuP)	0.2	0 W	0.3	5 W	0.1	9 W	
Heat Dissipation**		115	VAC	230	VAC	100	100 VAC	
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows Idle (S0)	253 E	Btu/hr	249 Btu/hr 256 Bt		Btu/hr		
	Windows Busy Typ (S0)	570 E	570 Btu/hr 584 Btu/hr 594 Btu/hr		Btu/hr			
	Windows Busy Max (S0)	) 833 Btu/hr 809 Btu/hr		826 Btu/hr				
	Sleep (S3)	2.83 Btu/hr	2.83Btu/hr	3.34 Btu/hr	2.83 Btu/hr	2.83Btu/hr	3.34 Btu/hr	
	Off (S5)	2.52 Btu/hr	2.52 Btu/hr	3.04 Btu/hr	2.52 Btu/hr	2.52 Btu/hr	3.04 Btu/hr	
	Zero Power Mode (EuP)	0.68	Stu/hr	1.19	Stu/hr	0.65 E	Btu/hr	

Example Configuration #3	Processor Info	1xIntel Xeon	E5-1280v3				
	Memory Info	HP 16GB (4x4	4GB) DDR3 18	866 ECC RAM			
	Graphics Info	1xNVIDIA K4100M					
	Disks/Optical/Floppy	2x1TB SATA	10K SFF/1xD	VD+-RW SATA	1		
	Power Supply	400W 90% C	ustom PSU				
	Other						
Energy Consumption		115	VAC	230	VAC	100	VAC
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	80	W	78	W	81	W
	Windows Busy Typ (S0)	0) 189 W 191 W 195 W			5 W		
	Windows Busy Max (S0)	0) 275 W 263 W		274	274 W		
	Sleep (S3)	0.90 W	0.90 W	1.06 W	0.90 W	0.90 W	1.06 W
	Off (S5)	0.73 W 0.73 W 0.89 W 0.73 W 0.73 W		0.73 W	0.89 W		
	Zero Power Mode (EuP)	0.2	0 W	0.3	4 W	0.1	9 W
Heat Dissipation**		115	VAC	230	VAC	100	VAC
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	273 E	Btu/hr	266 Btu/hr 276 Btu/hr		Btu/hr	
	Windows Busy Typ (S0)	645 E	645 Btu/hr 652 Btu/hr 665 Btu/hr		Btu/hr		
	938 Btu/hr	938 Btu/hr 897 Btu/hr 935 B		Btu/hr			
	Sleep (S3)	3.07 Btu/hr	3.07 Btu/hr	3.62 Btu/hr	3.07 Btu/hr	3.07 Btu/hr	3.62 Btu/hr
	Off (S5)	2.49 Btu/hr	2.49 Btu/hr	3.04 Btu/hr	2.49 Btu/hr	2.49 Btu/hr	3.04 Btu/hr
	Zero Power Mode (EuP)	0.68 E	Stu/hr	1.16 E	Stu/hr	2.22 E	Btu/hr



Declared Noise Emissions (Entry-level and High-end configurations)						
System Configuration Processor Info Intel Core i3-4130 2-core 3.4 GHz						
(Entry level) Memory Info 2 x 2 GB DDR3 1333 MHz Graphics Info NVIDIA Quadro K610M						
						Disks/Optical 1 x 2TB 7200 RPM SATA / Slim SuperMulti DVDRW SATA

<b>Declared Noise Emissions</b> (in accordance with ISO		Sound Power (LWAd, bels)	<b>Desktop Sound Pressure</b> (LpAm, decibels)
7779 and ISO 9296)	Idle	3.0 Bels	20 dB
	Hard drive Operating (random reads)	3.2 Bels	23dB
	DVD-ROM Operating (sequential reads)	4.3 Bels	32 dB

-,	Processor Info	Intel i3-4130 2-core 3.4 GHz		
(Entry level)	Memory Info	2 x 2 GB DDR3 1333 MHz		
	Graphics Info Intel HD Graphics 4400			
	Disks/Optical	2 x 480 GB SSD SATA / Slim SuperMulti DVDRW SATA		

<b>Declared Noise Emissions</b> (in accordance with ISO		Sound Power (LWAd, bels)	<b>Desktop Sound Pressure</b> (LpAm, decibels)
7779 and ISO 9296)	Idle	2.7 Bels	20 dB
I .	Hard drive Operating (random reads)	2.7 Bels	20 dB
	DVD-ROM Operating (sequential reads)	4.3 Bels	33 dB

System Configuration	Processor Info	Intel Xeon E3-1280 V3 4-core 3.6 GHz
(High-end)	Memory Info	4 x 8 GB DDR3 1333 MHz
	Graphics Info	NVIDIA Q4100M MXM
	Disks/Optical	2 x 500 GB 10K RPM SATA / Slim SuperMulti DVDRW SATA

1		Sound Power (LWAd, bels)	<b>Desktop Sound Pressure</b> (LpAm, decibels)
	Idle	3.0 Bels	21 dB
	Hard drive Operating (random reads)	3.8 Bels	28 dB
	DVD-ROM Operating (sequential reads)	4.3 Bels	32 dB

Environmental Requirements	Temperature	Operating: 40° to 95° F (5° to 35° C) Non-operating: -40° to 140° F (-40° to 60° C)
	Humidity	Operating: 8% to 85% RH, non-condensing Non-operating: 8% to 90% RH, non-condensing
	Maximum Altitude	Operating: 10,000 feet (3,000 m) Non-operating: 30,000 feet (9,100 m)
	<b>Dynamic</b> (new)	Shock Operating: ½-sine: 40g, 2-3ms (~62 cm/sec) Non-operating: ½-sine: 160 cm/s, 2-3ms (~105g) square: 422 cm/s, 20g  Vibration Operating random: 0.5g (rms), 5-300 Hz, up to 0.0025 g²/Hz Non-operating random: 2.0g (rms), 5-500 Hz, up to 0.0150 g²/Hz Values represent individual shock events and do not indicate repetitive shock events. Values do not indicate continuous vibration.
	Cooling	Above 5,000 ft (1524 m) altitude, maximum operating temperature is derated by 1.8° F (1° C) per 1,000 ft (305 m) elevation increase.

Physical Security and Serviceability		
Access Panel	Tool-less Includes system board and memory information	
Tool-less	Tool-less	
Hard Drives	Tool-less	
Expansion Cards	MXM graphics assembly is tool-less. MiniPCIe cards are screw-in.	
Processor Socket	Tool-less, except for the processor heatsink.	
Green User Touch Points	On tool-free internal chassis mechanisms	
Color-coordinated Cables and Connectors	When appropriate	
Memory	Tool-less	
System Board	Screw-In for motherboard, Rear IO and Side IO boards.	
Over-Temp Warning on Screen	Yes	



bystem rechineat spe		
Restore CD/DVD Set	Restores the computer to its original factory shipping operating system. Orderable with the workstation, or available from Support.	
<b>Dual Function Side Power</b>	Power on/off	
Switch		
	Causes a fail-safe power off when held for 4 seconds	
Cable Lock Support	Yes, Kensington Cable Lock (optional): Locks side cover and secures chassis from theft 3mm x 7mm slot at rear of system	
Solenoid Lock and Hood	No Solenoid Lock	
Sensor		
	Hood Sensor - The Sensor Kit detects when the access panel has been opened.	
Serial, Parallel, USB,	Enables or disables USB, audio, and network ports	
Audio, Network, Enable/Disable Port		
Control		
Power-On Password	Yes, prevents an unauthorized person from booting up the workstation	
Setup Password	Yes, prevents an unauthorized person from changing the workstation configuration	
3.3V Aux Power LED on	No	
System PCA	INU	
NIC LEDs (integrated) (Green & Amber)	Yes	
CPUs and Heatsinks	A T-15 Torx or flat blade screwdriver is needed to remove the CPU heatsink before the CPU can be removed. CPU removal is tool-less	
Power Supply Diagnostic LED	Yes	
Side Power Button	ACPI multi-function	
Side Power LED	Blue (normal), red (fault)	
Side Hard Drive Activity LED	Green	
Side ODD Activity LED	Present on an Optical Device	
Internal Stereo Speakers	Two 4W speakers	
System/Emergency ROM Flash Recovery	Recovers corrupted system BIOS.	
Cooling Solutions	Air cooled forced convection	
Power Supply Fans	Two 40 mm x 40 mm x 20 mm 4-wire PWM (not serviceable separately from the power supply)	
CPU Heatsink Fan	Two 80 mm blowers	
MXM Heatsink Fan	One 110 mm blower with MXM graphics assembly	
System Blower	110 mm blower	
HP Advanced System	HP Vision Diagnostics utility must be booted from USB or CD, and enables you to perform testing and to	
Diagnostics Offline Edition	view critical computer hardware and software configuration information from various sources.	
Access Panel Key Lock	No	
	J	



ACPI-Ready Hardware	<ul> <li>Advanced Configuration and Power Management Interface (ACPI).</li> <li>Allows the system to wake from a low power mode.</li> <li>Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system</li> </ul>
Trusted Platform Module Chip	Yes
Integrated Chassis Handles	One on top-rear of system
Power Supply	Tool-less
miniPCle Card Retention	2 × M2 screws
Flash ROM	Present
Diagnostic Power Switch LED on board	No
Clear Password Jumper	Present
Clear CMOS Button	Present
CMOS Battery Holder	Present
DIMM Connectors	Present - tool-less

BIOS	
BIOS 32-bit Services	Standard BIOS 32-bit Service Directory Proposal v0.4
АТАРІ	ATAPI Removable Media Device BIOS Specification Version 1.0.
BBS	BIOS Boot Specification v1.01.
WMI Support	WMI is Microsoft's implementation of Web-Based Enterprise Management (WBEM) for Windows. WMI is fully compliant with the Distributed Management Task Force (DMTF) Common Information Model (CIM) and WBEM specifications.
BIOS Boot Spec 1.01+	Provides more control over how and from what devices the workstation will boot.
BIOS Power On	Users can define a specific date and time for the system to power on.
ROM Based Computer Setup Utility (F10)	Review and customize system configuration settings controlled by the BIOS.
System/Emergency ROM Flash Recovery with Video	Recovers system BIOS in corrupted Flash ROM.
Replicated Setup	Saves BIOS settings to USB flash device in human readable file. Repset.exe utility can then replicate these settings on machines being deployed without entering Computer Configuration Utility (F10 Setup).
SMBIOS	System Management BIOS 2.7.1, for system management information.
Boot Control	Disables the ability to boot from removable media on supported devices.
Memory Change Alert	Alerts management console if memory is removed or changed.
Thermal Alert	<ul> <li>Monitors the temperature state within the chassis. Three modes:</li> <li>NORMAL - normal temperature ranges.</li> <li>ALERTED - excessive temperatures are detected. Raises a flag so action can be taken to avoid shutdown or provide for a smoother system shutdown.</li> <li>SHUTDOWN - excessive temperatures are encountered. Automatically shuts down the computer</li> </ul>



	without warning before hardware component damage occurs.
Remote ROM Flash	Provides secure, fail-safe ROM image management from a central network console.
ACPI (Advanced Configuration and Power Management Interface)	Allows the system to enter and resume from low power modes (sleep states).  Enables an operating system to control system power consumption based on the dynamic workload.  Makes it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system.  Supports ACPI 4.0 for full compatibility with 64-bit operating systems.
Ownership Tag	A user-defined string stored in non-volatile memory that is displayed in the BIOS splash screen.
Remote Wakeup/ Remote Shutdown	System administrators can power on, restart, and power off a client computer from a remote location.
Instantly Available PC (Suspend to RAM - ACPI sleep state S3)	Allows for very low power consumption with quick resume time.
Remote System Installation via F12 (PXE 2.1) (Remote Boot from Server)	Allows a new or existing system to boot over the network and download software, including the operating system.
ROM revision levels	Reports the system BIOS revision level in Computer Configuration Utility (F10 Setup). Version is available through an industry standard interface (SMBIOS) so that management SW applications can use and report this information.
System board revision level	Allows management SW to read revision level of the system board. Revision level is digitally encoded into the HW and cannot be modified.
Start-up Diagnostics (Power-on Self-Test)	Assesses system health at boot time with selectable levels of testing.
Auto Setup when new hardware installed	System automatically detects addition of new hardware.
Keyboard-less Operation	The system can be booted without a keyboard.
Localized ROM Setup	Common BIOS image supports System Configuration Utility (F10 Setup) menus in 12 languages with local keyboard mappings.
Asset Tag	Enables the user or IT administrator to set a unique tag string in non-volatile memory.
Per-slot Control	Allows I/O slot parameters (option ROM, enable/disable, bus latency) to be configured individually.
Adaptive Cooling	Control parameters are set according to detected hardware configuration for optimal acoustics.
Pre-boot Diagnostics	(Pre-video) critical errors are reported via beeps and blinks on the power LED.
Intel® Active Management Technology (AMT)	AMT 7.0; Allows workstation status to be monitored on a remote console
Digitally and Cryptographically Signed BIOS	Helps to prevent the installation of unauthorized versions of a BIOS (a rogue BIOS) from a virus, malware, or other code that could lead to compromised system security, data access, physical service, or even system board replacement.
Master Boot Record Protection	A feature in the HP BIOS that prevents changes and/or infections to the Master Boot Record. Useful in protecting from viruses
Boot Block Emergency Recovery Mode (BIOS Recovery)	The HP BIOS offers a write-protected boot block ROM that provides recovery from a failed flashing of the computer BIOS. This special recovery mode prevents the system from becoming unusable or "bricked" when a BIOS update is interrupted.



Industry Standard Specification Support	
Industry Standard	Revision Supported by the BIOS
UEFI Specification Revision	2.3.1
ACPI	Advanced Configuration and Power Management Interface, Version 4.0
ASF	No
ATA (IDE)	AT Attachment 6 with Packet Interface (ATA/ATAPI-6), Revision 3b
CD Boot	"El Torito" Bootable CD-ROM Format Specification Version 1.0
EDD	- Enhanced Disk Drive Specification Version 1.1 - BIOS Enhanced Disk Drive Specification Version 3.0
EHCI	Enhanced Host Controller Interface for Universal Serial Bus, Revision 1.0
PCI Express	- PCI Express Mini Card Electromechanical Specification Revision 1.2 - PCI Express Base Specification, Revision 2.0 - PCI Express Base Specification, Revision 3.0 - MXM Graphics Module Mobile PCI Express Module Electromechanical Specification Version 3.0, Revision 3.1
PMM	POST Memory Manager Specification, Version 1.01
SATA	- Serial ATA Specification, Revision 1.0a - Serial ATA II: Extensions to Serial ATA 1.0, Revision 2.6 - Serial ATA II Cables and Connectors Volume 2 Gold - SATA-IO SATA Revision 3.0 Specification
SPD	PC SDRAM Serial Presence Detect (SPD) Specification, Revision 1.2B
ТРМ	Trusted Computing Group TPM Specification Version 1.2
USB	- Universal Serial Bus Revision 1.1 Specifiation - Universal Serial Bus Revision 2.0 Specification - Universal Serial Bus Revision 3.0 Specification

Social and Environmental Responsibility		
Eco-Label Certifications &	This product has received or is in the process of being certified to the following approvals and may be	
Declarations	labeled with one or more of these marks:	
	<ul> <li>ENERGY STAR® (energy-saving features available on selected configurations-Windows only)</li> <li>US Federal Energy Management Program (FEMP)</li> <li>IT ECO declaration</li> </ul>	
Batteries	The battery in this product complies with EU Directive 2006/66/EC	
	Battery size: CR2032 (coin cell)	
	Battery type: Lithium Metal	
	The battery in this product does not contain:	
	Mercury greater than 5ppm by weight	
	Cadmium greater than 10ppm by weight	
	Lead greater than 40ppm by weight	



Restricted Material Usage	This product meets the material restrictions specified in HP's General Specification for the Environment.
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf
	Hewlett-Packard is committed to compliance with all applicable environmental laws and regulations,
	including the European Union Restriction of Hazardous Substances (RoHS) Directive. HP's goal is to exceed
Law Halagan Ctatament	compliance obligations by meeting the requirements of the RoHS Directive on a worldwide basis.  This product is low halogen except for power cords, cables and peripherals. Service parts obtained after
Low Halogen Statement	purchase may not be Low Halogen.
End-of-Life Management	Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas.
and Recycling	To recycle your product, please go to: http://www.hp.com/recycle or contact your nearest HP sales office.
	Products returned to HP will be recycled, recovered or disposed of in a responsible manner. This product is
	greater than 90% recyclable by weight when properly disposed of at end of life.
Hewlett-Packard	For more information about HP's commitment to the environment:
	Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
Information	Eco-label certifications
	http://www.hp.com/hpinfo/globalcitizenship/environment/productdesign/ecolabels.html
	intep., y www.np.com/npinto/globalcitizensinp/environinent/productuesign/ecolabets.ntml
	ISO 14001 certificates:
	http://www.hp.com/hpinfo/globalcitizenship/environment/operations/envmanagement.html
Additional Information	This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE)
	Directive – 2002/96/EC.
	<ul> <li>Plastic parts weighing over 25 grams used in the product are marked per ISO 11469 and ISO1043.</li> <li>This product is &gt;90% recycle-able when properly disposed of at end of life.</li> </ul>
	EPEAT Gold - ENERGY STAR qualified configurations of this product are in compliance with the IEEE 1680
	(EPEAT) standard at the Gold level where HP registers workstation products. See
	http://ww2.epeat.net/CompanyDetail.aspx?CompanyID=24 for registration status in your country.
Packaging	HP Workstation product packaging meets the HP General Specification for the Environment at
	http://www.hp.com/hpinfo/globalcitizenship/society/gen_specifications.html
	Does not contain restricted substances listed in HP Standard 011-1 General Specification for the
	Environment
	Does not contain ozone-depleting substances (ODS)
	Does not contain heavy metals (lead, mercury, cadmium or hexavalent chromium) in excess of 100
	ppm sum total for all heavy metals listed
	Maximizes the use of post-consumer recycled content materials in packaging materials
	All packaging material is recyclable
	All packaging material is designed for ease of disassembly
	Reduced size and weight of packages to improve transportation fuel efficiency
	Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards formattin
Packaging Materials	
Internal	
internat	Cushions and plastic bags made of low density polyethylene (LDPE).

Manageability	
Industry Standard	This product meets the following industry standard specifications for manageability functionality:
Specifications	DASH 1.1 required functionalities via integrated Intel LAN
Intel Active Management	Intel Active Management Technology (Intel® AMT) 9.0



### System Technical Specifications

#### Technology (AMT)

An advanced set of remote management features and functionality which provides network administrators the latest and most effective tools to remotely discover, heal, and protect networked client systems regardless of the system's health or power state. AMT 9.0 includes the following advanced management functions:

- Power Management (on, off, reset, graceful shutdown, sleep and hibernate)
- Hardware Inventory (includes BIOS and firmware revisions)
- Hardware Alerting
- Agent Presence
- System Defense Filters
- Serial Over LAN (SOL)
- IDE Redirect
- Remote Configuration
- TLS-PSK Setup and Configuration
- TLS-PKI Setup and Configuration
- Cisco NAC/SDN Support
- ME Wake-on-LAN
- DASH 1.1 compliance
- IPv6 Support
- Fast Call for Help a client inside or outside the firewall may initiate a call for help via BIOS screen, periodic connections, or alert triggered connection
- Remote Scheduled Maintenance pre-schedule when the PC connects to the IT or service provider console for maintenance. Remote PCs can get required patches, be inventoried, etc by connecting to their IT console or Service Provider when it's convenient
- Remote Alerts automatically alert IT or service provider if issues arise
- Access Monitor Provides oversight into Intel® AMT actions to support security requirements
- PC Alarm Clock
- Microsoft NAP Support
- Host Base set-up and configuration
- Management Engine (ME) firmware roll back
- Enhanced KVM resolution
- KVM Remote Control
- Local Time Sync to UTC
- Remote Memory Dump Command Creates memory dump for debug
- Wireless Management in Sleep States
- Desktop Wireless Manageability

### Intel® vPro™ Technology

The HP Z1 G2 Workstation supports Intel vPro technology when configured with a processor branded "featuring Intel vPro Technology"

### **Remote Manageability** Software Solutions

The HP Z1 Workstation is supported on the following remote manageability software consoles:

- LANDesk Management Suite (PSG recommended solution)
- Microsoft System Center Configuration Manager
- HP Client Automation Enterprise

For questions or support for manageability needs, please visit http://www.hp.com/go/easydeploy

System Software Manager For questions or support for SSM, please visit: http://www.hp.com/go/ssm

### Service, Support, and Warranty

On-site Warranty and Service (Note 1): One, Three, Four & Five -years (options available), limited warranty and service offering delivers on-site, next business-day (Note 2) service for parts and labor and includes free telephone support (Note 3) 8am - 5pm. Global coverage (Note 2) ensures that any product purchased in one country and transferred to another, non-restricted country will remain fully covered under the

### **System Technical Specifications**

original warranty and service offering.

**NOTE 1:** Terms and conditions may vary by country. Certain restrictions and exclusions apply.

**NOTE 2**: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

**NOTE 3:** Technical telephone support applies only to HP-configured, HP and HP-qualified, third-party hardware and software. Toll-free calling and 24x7 support service may not be available in some countries.

HP Care Pack Services extend service contracts beyond the standard warranties. Service starts from date of hardware purchase. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at http://www.hp.com/go/lookuptool. Additional HP Care Pack Services information by product is available at http://www.hp.com/hps/carepack. Service levels and response times for HP Care Packs may vary depending on your geographic location.

### Product Change Notification

- Program to proactively communicate Product Change Notifications (PCNs) and Customer Advisories by email to customers, based on a user-defined profile.
- PCNs provide advance notification of hardware and software changes to be implemented in the factory providing time to plan for transition.
- Customer Advisories provide concise, effective problem resolution, greatly reducing the need to call technical support.

### **Technical Specifications - Processors**

#### **Processors**

Intel® Xeon® processor E3-1280v3, Quad-Core, 8 MB cache, 3.6 GHz, up to 4.0 GHz with Intel Turbo Boost Technology

Intel® Xeon® processor E3-1245v3, Quad-Core, 8 MB cache, 3.4 GHz, up to 3.8 GHz with Intel Turbo Boost Technology

Intel® Xeon® processor E3-1225v3, Quad-Core, 8 MB cache, 3.2 GHz, up to 3.6 GHz with Intel Turbo Boost Technology

Intel® Core™ i5-4570 processor, Quad-Core, 6 MB cache, 3.2 GHz, up to 3.6 GHz with Intel Turbo Boost Technology

Intel® Core™ i3-4130 processor, Dual-Core, 4 MB cache, 3.4 GHz



### **Technical Specifications - Hard Drives**

SATA Hard Drives for HP	
Workstations	

500GB SATA 10K rpm SFF HDD

500GB Capacity

Height 0.6 in; 1.53 cm

Width **Media Diameter** 2.5 in; 6.36 cm **Physical Size** 2.75 in; 6.99 cm

Interface Serial ATA (6Gb/s) Up to 600MB/s

**Synchronous Transfer** 

Rate (Maximum)

64MB

**Buffer** Cache Adaptive Seek Time (typical reads, **Single Track** 

includes controller overhead, including

settling)

**Full Stroke** 

**Average** 

9.0ms (typical)

3.6ms

1.2ms (typical)

**Rotational Speed** 10K rpm

**Operating Temperature** 41° to 131° F (5° to 55° C)

### 1TB SATA 10K rpm SFF HDD

Capacity 1TB

Height 0.6 in; 1.53 cm

Width **Media Diameter** 2.5 in; 6.36 cm

**Physical Size** 2.75 in; 6.99 cm

Serial ATA (6Gb/s) **Interface Synchronous Transfer** Up to 600MB/s

Rate (Maximum)

**Buffer** 64MB Cache Adaptive

**Seek Time** (typical reads, **Single Track** 1.2ms (typical) includes controller **Average** 3.6ms overhead, including

**Full Stroke** settling)

9.0ms (typical)

10K rpm **Rotational Speed** 

**Operating Temperature** 41° to 131° F (5° to 55° C)

### 500GB SATA 7200 rpm 6Gb/s 3.5" HDD

Capacity 500GB Height 1 in; 2.54 cm

Width **Media Diameter** 3.5 in; 8.9 cm **Physical Size** 4 in; 10.17 cm

**Interface** Serial ATA (6.0Gb/s), NCQ enabled

**Synchronous Transfer** 

Rate (Maximum)

Up to 600MB/s

**Buffer 16MB** 

### **Technical Specifications - Hard Drives**

Seek Time (typical reads,<br/>includes controller<br/>overhead, including<br/>settling)Single Track<br/>Average2 msAverage<br/>Full Stroke11 ms

**Rotational Speed** 7,200 rpm **Logical Blocks** 976,773,168

**Operating Temperature** 41° to 131° F (5° to 55° C)

1TB SATA 7200 rpm 6Gb/s Capacity 3.5" HDD Height

**Capacity** 1 Terabyte (1000 GB) **Height** 1 in; 2.54 cm

Width Media Diameter 3.5 in; 8.9 cm
Physical Size 4 in; 10.17 cm

Up to 600MB/s

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer Rate (Maximum)

Buffer 64MB

Seek Time (typical reads,<br/>includes controller<br/>overhead, including<br/>settling)Single Track<br/>Average2 msAverage<br/>Full Stroke11 ms21 ms

**Rotational Speed** 7,200 rpm **Logical Blocks** 1,953,525,168

**Operating Temperature** 41° to 131° F (5° to 55° C)

2.0TB SATA 7200 rpm 6Gb/s 3.5" HDD **Capacity** 2TB

Height 1 in; 2.54 cm

Width Media Diameter 3.5 in; 8.9 cm
Physical Size 4 in; 10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

**Synchronous Transfer** Up to 600MB/s

Rate (Maximum)

Buffer 64MB

Seek Time (typical reads,<br/>includes controller<br/>overhead, including<br/>settling)Single Track<br/>Average1.0 ms<br/>11 msFull Stroke18 ms

Rotational Speed 7,200 rpm
Logical Blocks 3,907,029,168

**Operating Temperature** 41° to 131° F (5° to 55° C)

**3.0TB SATA 7200 rpm Capacity** 3.0TB

Not specified

## QuickSpecs

### **Technical Specifications - Hard Drives**

6Gb/s 3.5" HDD

**Height** 1 in; 2.54 cm

Width Media Diameter 3.5 in; 8.9 cm

**Physical Size** 4 in; 10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Up to 600MB/s

Buffer 64MB

Seek Time (typical reads, includes controller overhead, including

Single Track 0.6 ms

Average 11 ms

settling) Full Stroke

**Rotational Speed** 7,200 rpm

**Operating Temperature** 41° to 131° F (5° to 55° C)

SATA SSDs for HP Workstations HP 256GB SATA 6Gb/s SSD Capacity 256GB

**Height** 0.28 in; 0.7 cm Interface SATA 6Gb/s

Synchronous Transfer Rate (Maximum)

Up to 500MB/s (Sequential Read)

**Operating Temperature** 32° to 158° F (0° to 70° C)

HP 256GB mSATA 6Gb/s

SSD

Capacity 256GB

Interface 6Gb/s SATA

HP 512GB SATA 6Gb/s SSD Capacity 512GB

**Height** 0.28 in; 0.7 cm

Width Physical Size 2.5 in; 6.36 cm

Interface SATA 6Gb/s

**Synchronous Transfer** 

Rate (Maximum)

Up to 500MB/s (Sequential Read)

**Operating Temperature** 32° to 158° F (0° to 70° C)

Seagate 600 Pro 120GB

**SATA SSD** 

Capacity 120GB

**Height** 0.276 in; 0.7 cm

Width Physical Size 2.76 in; 7.01 cm

Interface SATA 6Gb/s
Synchronous Transfer Up to 600MB/s

Rate (Maximum)

**Operating Temperature** 32° to 158° F (0° to 70° C)

**Technical Specifications - Hard Drives** 

Seagate 600 Pro 240GB

**SATA SSD** 

Capacity 240GB

Height 0.28 in; 0.7 cm

Width **Physical Size** 2.76 in; 7.01 cm

Interface SATA 6Gb/s **Synchronous Transfer** Up to 600MB/s

Rate (Maximum)

**Operating Temperature** 32° to 158° F (0° to 70° C)

Seagate 600 Pro 480GB

**SATA SSD** 

Capacity 480GB

Height 0.28 in; 0.7 cm

Width **Physical Size** 2.76 in; 7.01 cm

Interface SATA 6Gb/s **Synchronous Transfer** Up to 600MB/s

Rate (Maximum)

**Operating Temperature** 32° to 158° F (0° to 70° C)



### Technical Specifications - Graphics

**Integrated Intel HD** Graphics (Z230/Z1G2) **Form Factor** Integrated in select Intel Xeon E3, Intel Core i7, and Intel Core i5 processors.

Check specific platform specifications for selections.

**Graphics Controller** Intel HD Graphics

Memory Unified Memory Architecture (UMA) frame buffer. Graphics memory is shared

> with system memory. Size selectable between 64 MB to 512 MB via BIOS setting. Default size is 64 MB. Additional memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (Intel DVMT 5.0), to provide an optimal balance between graphics and system memory use.

**Connectors** Check system platform specifications where Intel HD Graphics are available.

**Maximum Resolution** Display Port: 2560 x 1600

> DVI: 1920x1200 VGA: 2048x1536

**NOTE:** For DVI and VGA outputs, separate adapters may be required.

**Shading Architecture** Shader Model 5.0 **Supported Graphics APIs** OpenGL 4.0

DirectX 11.1

**Available Graphics** 

Windows 7 **Drivers** Windows 8.1

**NVIDIA Quadro K610M 1GB Graphics** 

Form Factor MXM v3.1 Type A (82mm x 70mm)

**Graphics Controller** N15M-Q3, 954MHz core clock

192 CUDA cores

**Bus Type** PCI Express Gen 3 x16 (part of MXM v3.1 connector)

1GB GDDR5 Memory

64 bit wide interface

2600MHz. 20.8 GB/s

**Connectors** One MXM v3.1 connector (285-pin)

**Maximum Resolution** 2 x 3840x2160 @ 60Hz digital displays

In Z1 G2 application:

- Internal Display: 2560x1440

- External Display via DP connector: 2560x1600

- External Display via optional Thunderbolt module: Two 3840x2160

RAMDAC Not Applicable

**Image Quality Features** Each color component can be processed at up to 32-bit floating point precision

> and displayed at up to 12-bit precision. Advanced FXAA and TXAA antialiasing. 16K Texture and Render Processing.

MPEG-2 HD and WMV HD video playback (1920x1080p).

H.264 hardware decode acceleration. Nvidia Scalable Geometry Engine.

**Shading Architecture** Shader Model 5.0 support

### **Technical Specifications - Graphics**

Supported Graphics APIs Full IEEE 764-2008 32-bit

DirectX 11.1 Shader Model 5.0

OpenGL 4.3

Compute API support for NVIDIA CUDA C, CUDA C++, DirectCompute 5.0,

OpenCL, Java, Python and Fortran

**Available Graphics** 

**Drivers** 

Windows 7 64-bit Windows 8.1 64-bit

SUSE Linux Enterprise Desktop 11 64-bit Red Hat Enterprise Linux 6 Workstation 64-bit

See www.hp.com/go/support for HP supported NVIDIA graphics drivers

NVIDIA Quadro K2100M 2GB Graphics

Form Factor MXM v3.1 Type A (82mm x 70mm)

**Graphics Controller** N15P-Q3, 665MHz core clock

576 CUDA cores

**Bus Type** PCI Express Gen 3 x16 (part of MXM v3.1 connector)

Memory 2GB GDDR5

128 bit wide interface

3000MHz, 48 GB/s

**Connectors** One MXM v3.1 connector (285-pin)

**Maximum Resolution** 2 x 3840x2160 @ 60Hz digital displays

In Z1 G2 application:

- Internal Display: 2560x1440

- External Display via DP connector: 2560x1600

- External Display via optional Thunderbolt module: Two 3840x2160

**RAMDAC** Not Applicable

Image Quality Features Each color component can be processed at up to 32-bit floating point precision

and displayed at up to 12-bit precision. Advanced FXAA and TXAA antialiasing. 16K Texture and Render Processing.

MPEG-2 HD and WMV HD video playback (1920x1080p).

H.264 hardware decode acceleration. Nvidia Scalable Geometry Engine.

AES-128 CTR/CBC/ECB decryption modes supported.

Nvidia 3D Vision Pro

**Shading Architecture** Shader Model 5.0 support **Supported Graphics APIs** Full IEEE 764-2008 32-bit

DirectX 11.1 Shader Model 5.0

OpenGL 4.3

Compute API support for NVIDIA CUDA C, CUDA C++, DirectCompute 5.0,

OpenCL, Java, Python and Fortran



### **Technical Specifications - Graphics**

**Available Graphics** 

**Drivers** 

Windows 7 64-bit Windows 8.1 64-bit

SUSE Linux Enterprise Desktop 11 64-bit Red Hat Enterprise Linux 6 Workstation 64-bit

See www.hp.com/go/support for HP supported NVIDIA graphics drivers

NVIDIA Quadro K3100M 4GB Graphics **Form Factor** MXM v3.1 Type B (82mm x 105mm)

**Graphics Controller** N15E-Q1, 705MHz core clock

768 CUDA cores

**Bus Type** PCI Express Gen 3 x16 (part of MXM v3.1 connector)

Memory 4GB GDDR5

256 bit wide interface

3200MHz, 102.4 GB/s

**Connectors** One MXM v3.1 connector (285-pin)

Maximum Resolution 2 x 3840x2160 @ 60Hz digital displays

In Z1 G2 application:

- Internal Display: 2560x1440

- External Display via DP connector: 2560x1600

- External Display via optional Thunderbolt module: Two 3840x2160

RAMDAC Not Applicable

Image Quality Features Each color component can be processed at up to 32-bit floating point precision

and displayed at up to 12-bit precision. Advanced FXAA and TXAA antialiasing. 16K Texture and Render Processing.

MPEG-2 HD and WMV HD video playback (1920x1080p).

H.264 hardware decode acceleration. Nvidia Scalable Geometry Engine.

AES-128 CTR/CBC/ECB decryption modes supported.

Nvidia 3D Vision Pro

**Shading Architecture** Shader Model 5.0 support **Supported Graphics APIs** Full IEEE 764-2008 32-bit

DirectX 11.1 Shader Model 5.0

OpenGL 4.3

Compute API support for NVIDIA CUDA C, CUDA C++, DirectCompute 5.0,

OpenCL, Java, Python and Fortran

**Available Graphics** 

**Drivers** 

Windows 7 64-bit Windows 8.1 64-bit

SUSE Linux Enterprise Desktop 11 64-bit Red Hat Enterprise Linux 6 Workstation 64-bit

See www.hp.com/go/support for HP supported NVIDIA graphics drivers

### **Technical Specifications - Graphics**

**NVIDIA Quadro K4100M 4GB Graphics** 

**Form Factor** MXM v3.1 Type B (82mm x 105mm)

**Graphics Controller** N15E-Q3, 705MHz core clock

1152 CUDA cores

**Bus Type** PCI Express Gen 3 x16 (part of MXM v3.1 connector)

Memory 4GB GDDR5

256 bit wide interface

3200MHz. 102.4 GB/s

**Connectors** One MXM v3.1 connector (285-pin) **Maximum Resolution** Maximum number of active displays: 4

In Z1 G2 application:

- Internal Display: 2560x1440

- External Display via DP connector: 2560x1600

- External Display via optional Thunderbolt module: Two 3840x2160

**RAMDAC** Not Applicable

**Image Quality Features** Each color component can be processed at up to 32-bit floating point precision

> and displayed at up to 12-bit precision. Advanced FXAA and TXAA antialiasing. 16K Texture and Render Processing.

MPEG-2 HD and WMV HD video playback (1920x1080p).

H.264 hardware decode acceleration. Nvidia Scalable Geometry Engine.

AES-128 CTR/CBC/ECB decryption modes supported.

Nvidia 3D Vision Pro

**Shading Architecture** Shader Model 5.0 support **Supported Graphics APIs** Full IEEE 764-2008 32-bit

DirectX 11.1 Shader Model 5.0

OpenGL 4.3

Compute API support for NVIDIA CUDA C, CUDA C++, DirectCompute 5.0,

OpenCL, Java, Python and Fortran

**Available Graphics** 

**Drivers** 

Windows 7 64-bit Windows 8.1 64-bit

SUSE Linux Enterprise Desktop 11 64-bit Red Hat Enterprise Linux 6 Workstation 64-bit

See www.hp.com/go/support for HP supported NVIDIA graphics drivers

### Technical Specifications - Optical and Removable Storage

**HP Slim DVD-ROM Drive** 

**Description** 12.7mm high, tray-load

**Mounting Orientation** Either horizontal or vertical

Interface TypeSATA / ATAPIDimensions (WxHxD)128 x 14 x 128mm

**Disc Capacity DVD-ROM**Single layer: Up to 4.7 GB

Double layer: Up to 8.5 GB

Access Times DVD-ROM Single Layer <110 ms (typical)

CD-ROM Mode 1 <110 ms (typical)
Full Stroke DVD <230 ms (seek)

Full Stroke CD <220 ms (seek)

Power Source SATA DC power receptacle

**DC Power Requirements** 5 VDC ± 5%-100 mV ripple p-p

**DC Current** 5 VDC - <800mA typical, < 1600 mA maximum

Operating Environmental Temperature

(all conditions noncondensing) **Temperature** 41° to 122° F (5° to 50° C)

Relative Humidity 10% to 80% Maximum Wet Bulb 84° F (29° C)

**Temperature** 

Operating Systems
Supported

Windows 8 32-bit and 64-bit, Windows 7 Professional 32-bit and 64-bit, Windows Vista Business 64\*, Windows Vista Business 32\*, Windows Vista Home Basic 32\*, Windows 2000, Windows XP Professional or Windows XP

Home 32\*.

Red Hat Enterprise Linux(RHEL) WS4\*\*, 5, 6 Desktop/Workstation,

Removed reference to "Novell" because of acquisition and changed product

reference to "SUSE Linux Enterprise Desktop 10 & 11",

No driver is required for this device. Native support is provided by the

operating system.

HP Slim SuperMulti DVDRW SATA Drive **Description** 12.7mm high, tray-load **Mounting Orientation** Either horizontal or vertical

Interface Type SATA/ATAPI

**Dimensions** (WxHxD) 128 x 14 x 128mm

Supported Media Types DVD-RAM

DVD+R
DVD+RW
DVD+R DL
DVD-R DL
DVD-R
DVD-RW
CD-R
CD-RW

**Disc Capacity DVD-ROM** 8.5 GB DL or 4.7 GB standard

### Technical Specifications - Optical and Removable Storage

**Access Times Full Stroke DVD** < 230 ms (seek)

**Full Stroke CD** < 220ms (seek)

**Maximum Data Transfer** 

Rates

**CD ROM Read** CD-ROM, CD-R Up to 24X

CD-RW Up to 24X

**DVD ROM Read** DVD-RAM Up to 8X

DVD+RW Up to 8X DVD-RW Up to 8X DVD+R DL Up to 8X DVD-R DL Up to 8X DVD-ROM Up to 8X DVD-ROM DL Up to 8X DVD+R Up to 8X DVD-R Up to 8X

**Power** Source SATA DC power receptacle

> **DC Power Requirements** 5 VDC ± 5%-100 mV ripple p-p

**DC Current** 5 VDC -< 800 mA typical, <1600 mA maximum

**Operating Environmental Temperature** 

(all conditions noncondensing)

41° to 122° F (5° to 50° C)

**Relative Humidity** 10% to 80% **Maximum Wet Bulb** 84° F (29° C)

**Temperature** 

**Operating Systems** 

Supported

Windows 8 32-bit and 64-bit, Windows 7 Professional 32-bit and 64-bit, Windows Vista Business 64\*, Windows Vista Business 32\*, Windows Vista

Home Basic 32\*, Windows 2000, Windows XP Professional or Windows XP

Home 32\*.

Red Hat Enterprise Linux(RHEL) WS4\*\*, 5, 6 Desktop/Workstation

SUSE Linux Enterprise Desktop 10 & 11

No driver is required for this device. Native support is provided by the

operating system.

**Kit Contents** HP SATA SuperMulti DVD Writer drive, Cyberlink Power2Go Software, Cyberlink

PowerDVD Software, installation guide, and DVD+R media.

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**HP Slim Blu-ray Writer** 

**Description** 

12.7mm high, tray-load

**Mounting Orientation** 

Horizontal

**Interface Type** 

SATA

**Dimensions** (WxHxD)

128 x 14 x 128mm

**Supported Media Types** 

**BD-ROM** 

BD-R

**BD-RE** 



### Technical Specifications - Optical and Removable Storage

DVD-RAM DVD+R DVD+RW DVD+R DL DVD-R DL DVD-RW CD-R CD-RW

**Disc Capacity DVD-ROM** 8.5 GB DL or 4.7 GB standard

CD-ROM 650MB CD-ROM (Read Only)

800/700/650MB CD-Recordable (Read & Write) 700/650MB CD-Rewritable (Read & Write) 700/650MB High Speed CD-Rewritable (Read &

Write)

700/650MB Ultra & Ultra+ Speed CD-Rewritable

(Read & Write)

**Blu-ray** 50 GB DL or 25 GB standard

Full Stroke DVD < 200ms (seek)
Full Stroke CD < 200ms (seek)
Blu-ray < 230ms (seek)

**Startup Time** (Time to drive ready from tray loading)

BD-ROM (SL/DL) 25S / 28S BD-R (SL/DL) 25S / 28S BD-RE (SL/DL) 25S / 28S DVD-ROM (SL/DL) 18S / 18S DVD-R (SL/DL) 25S / 25S

DVD-RW 25S

DVD+R (SL/DL) 25S / 25S

DVD+RW 25S DVD-RAM 45S CD-ROM 15S

Maximum Data Transfer CD ROM Read

**Rates** 

**Access Times** 

ROM Read CD-ROM, CD-R Up to 24X

CD-RW Up to 24X

**DVD ROM Read** DVD-RAM Up to 8X

DVD+RW Up to 8X
DVD-RW Up to 8X
DVD+R DL Up to 8X
DVD-R DL Up to 8X
DVD-ROM Up to 8X
DVD-ROM DL Up to 8X
DVD-ROM DL Up to 8X
DVD+R Up to 8X
DVD-R Up to 8X

Blu-ray BD-ROM Up to 6X

BD-ROM DL Up to 6X BD-R Up to 6X BD-R DL Up to 6X BD-R Up to 6X



### Technical Specifications - Optical and Removable Storage

BD-RE SL/DL Up to 6X

BD-RE TL 4.8x

**Power** Source SATA DC power receptacle

**DC Power Requirements** 5 VDC ± 5%-100 mV ripple p-p

**DC Current** 5 VDC -900 mA typical, 2000mA maximum

84° F (29° C)

**Operating Environmental Temperature** 

(all conditions noncondensing) **Temperature** 41° to 122° F (5° to 50° C)

**Relative Humidity** 15% to 80%

Temperature

**Maximum Wet Bulb** 

**Operating Systems** 

**Supported** 

Windows 8 32-bit and 64-bit, Windows 7 Professional 32-bit and 64-bit, Windows Vista Business 64\*, Windows Vista Business 32\*, Windows Vista

Home Basic 32\*, Windows 2000, Windows XP Professional or Windows XP

Home 32\*.

Red Hat Enterprise Linux(RHEL) WS4, 5, 6 Desktop/Workstation,

SUSE Linux Enterprise Desktop 10 & 11

\* No driver is required for this device. Native support is provided by the

operating system.

Kit Contents HP Blue Laser RW Drive, Cyberlink Power2Go Software, Cyberlink PowerDVD

Software, installation guide.

As Blu-Ray is a new format containing new technologies, certain disc, digital connection, compatibility and/or performance issues may arise, and do not constitute defects in the product. Flawless playback on all systems is not guaranteed. In order for some Blu-Ray titles to play, they may require a DVI or HDMI digital connection and your display may require HDCP support. HD-DVD

movies cannot be played on this workstation.



### **Technical Specifications - Controller Cards**

**Operating** 

Supported

HP Thunderbolt 2-port AiO Module **Data Transfer Rate** Supports up to 20 Gb/s (20,000 Mb/s)

**Devices Supported** Thunderbolt™ certified devices

**Ports** Two (2) Thunderbolt™ 2 external 20-Pin output connectors (Side)

**Internal Connectors** TBD ??

System Requirements Genuine Windows 7 Professional 64-bit, Genuine Windows 8.1 64-bit, Intel i5

series or higher processor, 128-MB RAM, 1-GB Hard Drive, available PCIe slot.

**Temperature - Operating** 50° to 131° F (10° to 55° C)

**Temperature - Storage** -22° to 140° F (-30° to 60° C)

**Relative Humidity -** 20% to 80%

**Compliances** FCC Part 15B, cULus 60950, CE Mark EN55022B(1995)/EN55024-1998 STD,

Taiwan BSMI CNS13438, Korea MIC

**Operating Systems** Genuine Windows 7 Professional 64-bit, Genuine Windows 8.1 64-bit.

**Kit Contents** HP Thunderbolt™ 2 Module, user documentation and warranty card.

**Warranty** The HP Thunderbolt<sup>™</sup> 2 Module has a one-year Limited Warranty or the

remainder of the warranty of the HP supported product in which it is installed. Technical support is available seven days a week, 24 hours a day, by phone, as well as online support forums. Certain restrictions and exclusions apply.

### Technical Specifications - Networking and Communications

Integrated Intel I217LM PCIe GbE Controller

**Connector** RJ-45

Controller Intel I217LM GbE platform LAN connect networking controller

Memory 3 KB Tx and 3KB Rx FIFO packet buffer memory

**Data Rates Supported** 10/100/1000 Mbps

Compliance 802.1as/1588, 802.1p, 802.1Q, 802.3, 802.3ab, 802.3az, 802.3i, 802.3u,

802.3z

**Bus Architecture** PCI Express and SMBus

**Data Transfer Mode** PCIe-based interface for active state operation (SO state) and SMBus for host

and management traffic (Sx low power state)

**Power Requirement** Requires 3.3V (integrated regulators for core Vdc)

**Boot ROM Support** Yes

Network Transfer Mode Full-duplex; Half-duplex (not supported for the 1000BASE-T transceiver)

**Network Transfer Rate** 10BASE-T (half-duplex) 10 Mbps

10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps

Management Capabilities vPro, WOL, auto MDI crossover, PXE, iSCSI Boot, Muti-port teaming, RSS, ACPI,

Advanced cable diagnostic, loopback modes,

AMT 9.0 support, Circuit Breaker, VLAN, Multicast Listener Discovery (MLD)

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